



Pyramid KD2440 PEEK

Ceramic filled ESD PEEK for Test Sockets

General	ASTM #	US Value	SI Unit
Composition	---	Ceramic ESD PEEK	
Density, lb/in ³	D792	0.055	1.52 g/cm ³
Mechanical			
Tensile Strength (Break), Kpsi	D638	13.8	95 MPa
Tensile Modulus, Mpsi	D638	0.67	5 GPa
Elongation (Break), %	D638	>10 %	
Flexural Strength (Yield) Kpsi	D790	24	165 MPa
Flexural Modulus Mpsi	D790	0.65	4.8 GPa
Izod, Notched, ft-lb/in @1/8"	D256	1	53 J/cm
Thermal			
Melting Point, °F	DSC	645	341°C
Tg (Glass Transition), °F	DSC	290	143°C
HDT@ 66 psi, °F	D648	> 500	> 260°C
CTE, linear $\mu\text{in/in-}^\circ\text{F}$ (< Tg)	D696	2×10^{-5}	3.6×10^{-5} $\mu\text{m/m-}^\circ\text{C}$
Electrical			
Volume Resistivity, Ohm-cm	D257	1e9 – 1e12	
Surface Resistivity, Ohm/sq	D257	1e9 – 1e12	

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